



September 24, 2003

To: Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Fr: George O. Saile, Reg. No. 19,572
28 Davis Avenue
Poughkeepsie, N.Y. 12603

Subject:

Serial No. 10/613,694 07/03/03

Yang-Tung Fan et al.

NEW BUMPING PROCESS TO INCREASE
BUMP HEIGHT AND TO CREATE A MORE
ROBUST BUMP STRUCTURE

Grp. Art Unit:

INFORMATION DISCLOSURE STATEMENT

Enclosed is Form PTO-1449, Information Disclosure Citation
In An Application.

The following Patents and/or Publications are submitted to
comply with the duty of disclosure under CFR 1.97-1.99 and
37 CFR 1.56. Copies of each document is included herewith.

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being
deposited with the United States Postal Service as first class
mail in an envelope addressed to: Commissioner for Patents,
P.O. Box 1450, Alexandria, VA 22313-1450, on September 26, 2003.

Stephen B. Ackerman, Reg.# 37761

Signature/Date

Stephen B. Ackerman 9/26/03

TSMC-00-776B


U.S. Patent 5,904,156 to Advocate, Jr. et al., "Dry Film Resist Removal in the Presence of Electroplated C4's," discloses a process for a dry film resist removal in the presence of electroplated bumps.

U.S. Patent 6,211,052 to Farnworth, "Mask Repattern Process," discloses a UBM and bump process using photoresist.

U.S. Patent 5,914,274 to Yamaguchi et al., "Substrate on which Bumps are Formed and Method of Forming the Same," discloses a substrate on which bumps are formed and a method of forming same.

U.S. Patent 5,903,058 to Akram, "Conductive Bumps on Die for Flip Chip Application," discloses a process for conductive bumps on a die.

Sincerely,


Stephen B. Ackerman,
Reg. No. 37761

